Database:

# Refine Search



#### Search Results -

Terms	Documents
L2 and (second near2 oxide)	2

US Pre-Grant Publication Full-Text Database
US Patents Full-Text Database
US OCR Full-Text Database
EPO Abstracts Database
JPO Abstracts Database
Derwent World Patents Index

IBM Technical Disclosure Bulletins

Search:

Refine Search

Recall Text 🗢

Clear

Interrupt

#### Search History

DATE: Wednesday, December 31, 2003 Printable Copy Create Case

Set Name side by side		Hit Count S	Set Name result set
DB=US	SPT; PLUR=YES; OP=ADJ		
<u>1.4</u>	L2 and (second near2 oxide)	2	<u>L4</u>
<u>L.3</u>	L2 and (wet adj tool)	0	<u>L3</u>
<u>L.2</u>	L1 and mask and resist and (copper near2 seed)	34	<u>L2</u>
T.1	interconnect and barrier and (plating near3 copper)	539	T.1

#### END OF SEARCH HISTORY

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**Search Results -** Record(s) 1 through 2 of 2 returned.

1. Document ID: US 6420262 B1

L4: Entry 1 of 2

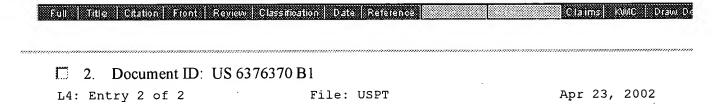
File: USPT

Jul 16, 2002

US-PAT-NO: 6420262

DOCUMENT-IDENTIFIER: US 6420262 B1

TITLE: Structures and methods to enhance copper metallization



US-PAT-NO: 6376370

DOCUMENT-IDENTIFIER: US 6376370 B1

\*\* See image for Certificate of Correction \*\*

TITLE: Process for providing seed layers for using aluminum, copper, gold and silver metallurgy process for providing seed layers for using aluminum, copper, gold and silver metallurgy

Full   Title   Citation   Front   Review   Classification   Date   Re	telence Claims KWC Diaw D
Clear Generate Collection Print Fwd	Refs Bkwd Refs Generate OACS
Terms	Documents
L2 and (second near2 oxide)	2

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# Refine Search

#### Search Results -

Terms	Documents
L12 and patterning	3

	US Pre-Grant Publication Full-Text Database
	US Patents Full-Text Database
	US OCR Full-Text Database
Database:	EPO Abstracts Database
	JPO Abstracts Database
	Derwent World Patents Index
	IBM Technical Disclosure Bulletins

Search:

L13	,		Refine Search
	Recall Text 👄	Clear	Interrupt

### **Search History**

# DATE: Wednesday, December 31, 2003 Printable Copy Create Case

Set Name side by side	Query	Hit Count	<u>Set</u> <u>Name</u> result set
DB=U	ISPT; PLUR=YES; OP=ADJ		
<u>L13</u>	L12 and patterning	3	<u>L13</u>
<u>L12</u>	L11 and etching	8	<u>L12</u>
<u>L11</u>	L10 and oxides	15	<u>L11</u>
<u>L10</u>	L8 and interconnect and barrier and (copper adj seed) and plating	16	<u>L10</u>
<u>L9</u>	L8 and interconnect and barrier and (copper adj seed) and plating and (second near2 oxide)	0	<u>L9</u>
<u>L8</u>	tool adj set	4771	<u>L8</u>
<u>L7</u>	(wet adj tool adj set)	1	<u>L7</u>
<u>L6</u>	L1 and (wet adj tool adj set)	0	<u>L6</u>
<u>L5</u> -	L2 and (wet adj tool adj set)	0	<u>L5</u>
<u>L4</u>	L2 and (second near2 oxide)	2	<u>1.4</u>
<u>L3</u>	L2 and (wet adj tool)	0	<u>L3</u>
<u>1.2</u>	L1 and mask and resist and (copper near2 seed)	34	<u>1.2</u>

<u>L.1</u> interconnect and barrier and (plating near3 copper)

539 <u>L1</u>

**END OF SEARCH HISTORY** 

### Hit List

Clear Generate Collection Print Fwd Refs Bkwd Refs **Generate OACS** 

**Search Results -** Record(s) 1 through 3 of 3 returned.

1. Document ID: US 6387800 B1

L13: Entry 1 of 3

File: USPT

May 14, 2002

US-PAT-NO: 6387800

DOCUMENT-IDENTIFIER: US 6387800 B1

TITLE: Method of forming barrier and seed layers for electrochemical deposition of

copper

Full Title Citation Front Review Classification Date Reference Claims KMC Draw De

2. Document ID: US 6143126 A

L13: Entry 2 of 3

File: USPT

Nov 7, 2000

US-PAT-NO: 6143126

DOCUMENT-IDENTIFIER: US 6143126 A

TITLE: Process and manufacturing tool architecture for use in the manufacture of

one or more metallization levels on an integrated circuit

Full Title Citation Front Review Classification Date Reference

3. Document ID: US 6120641 A

L13: Entry 3 of 3

File: USPT

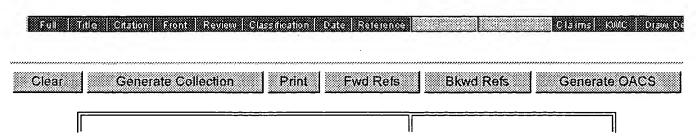
Sep 19, 2000

US-PAT-NO: 6120641

DOCUMENT-IDENTIFIER: US 6120641 A

TITLE: Process architecture and manufacturing tool sets employing hard mask patterning for use in the manufacture of one or more metallization levels on a

workpiece



Terms	Documents
L12 and patterning	3

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### Hit List

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**Search Results -** Record(s) 1 through 8 of 8 returned.

1. Document ID: US 6645356 B1

L12: Entry 1 of 8

File: USPT

Nov 11, 2003

US-PAT-NO: 6645356

DOCUMENT-IDENTIFIER: US 6645356 B1

TITLE: Methods and apparatus for processing the surface of a microelectronic

workpiece

Full Title Citation Front Review Classification Date Reference Claims KMC Draw Da 2. Document ID: US 6387800 B1 L12: Entry 2 of 8 File: USPT May 14, 2002

US-PAT-NO: 6387800

DOCUMENT-IDENTIFIER: US 6387800 B1

TITLE: Method of forming barrier and seed layers for electrochemical deposition of

copper

Full Title Citation Front Review Classification Date Reference

3. Document ID: US 6376374 B1

L12: Entry 3 of 8

File: USPT

Apr 23, 2002

US-PAT-NO: 6376374

DOCUMENT-IDENTIFIER: US 6376374 B1

TITLE: Process and manufacturing tool architecture for use in the manufacturing of

one or more protected metallization structures on a workpiece

Full Title Criation Front Review Classification Date Reference Claims Quilt Draw De

4. Document ID: US 6309524 B1

L12: Entry 4 of 8

File: USPT

Oct 30, 2001

Record List Display Page 2 of 3

US-PAT-NO: 6309524

DOCUMENT-IDENTIFIER: US 6309524 B1

\*\* See image for <u>Certificate of Correction</u> \*\*

TITLE: Methods and apparatus for processing the surface of a microelectronic

workpiece

5. Document ID: US 6309520 B1

L12: Entry 5 of 8

File: USPT

Full Title Citation Front Review Classification Date Reference Claims KMC Draw D

Oct 30, 2001.

US-PAT-NO: 6309520

DOCUMENT-IDENTIFIER: US 6309520 B1

\*\* See image for Certificate of Correction \*\*

TITLE: Methods and apparatus for processing the surface of a microelectronic

workpiece

Full Title Citation Front Review Classification Date Reference

6. Document ID: US 6303010 B1

L12: Entry 6 of 8

File: USPT

Oct 16, 2001

US-PAT-NO: 6303010

DOCUMENT-IDENTIFIER: US 6303010 B1

\*\* See image for Certificate of Correction \*\*

TITLE: Methods and apparatus for processing the surface of a microelectronic workpiece

Full Title Citation Front Review Classification Date Reference Claims KNNC Draw De 7. Document ID: US 6143126 A L12: Entry 7 of 8 File: USPT Nov 7, 2000

US-PAT-NO: 6143126

DOCUMENT-IDENTIFIER: US 6143126 A

TITLE: Process and manufacturing tool architecture for use in the manufacture of

one or more metallization levels on an integrated circuit

Full Title Citation Front Review Classification Date Reference Claims SUIC District.

8. Document ID: US 6120641 A

L12: Entry 8 of 8

File: USPT

Sep 19, 2000

US-PAT-NO: 6120641

DOCUMENT-IDENTIFIER: US 6120641 A

TITLE: Process architecture and manufacturing  $\underline{\text{tool sets}}$  employing hard mask patterning for use in the manufacture of one or more metallization levels on a workpiece

Full Title Citation Front Review Classification Date Refere	nes Cleims Kwes Drewid:
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Terms	Documents
L11 and etching	8

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